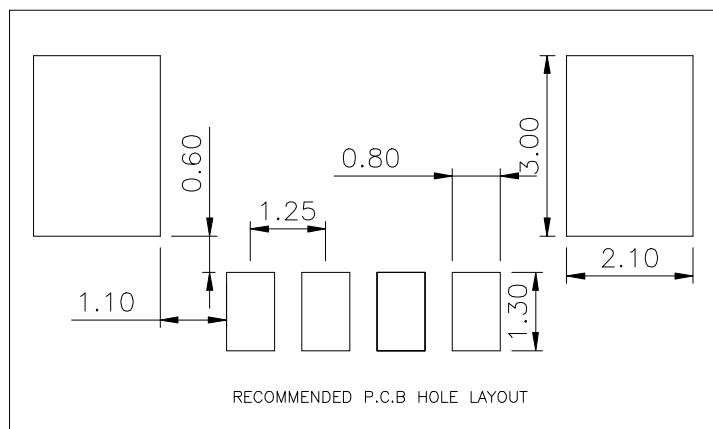
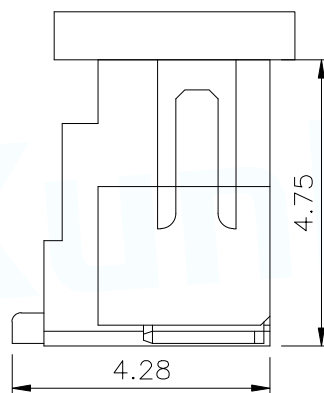
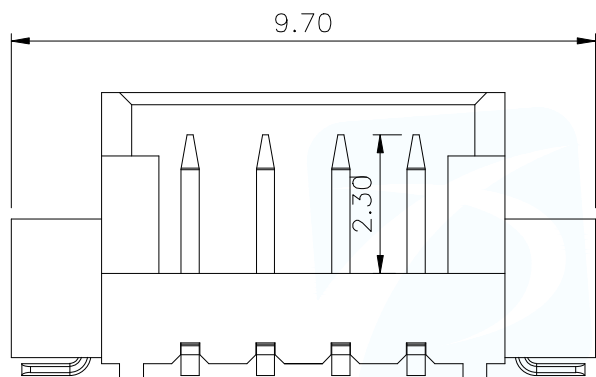
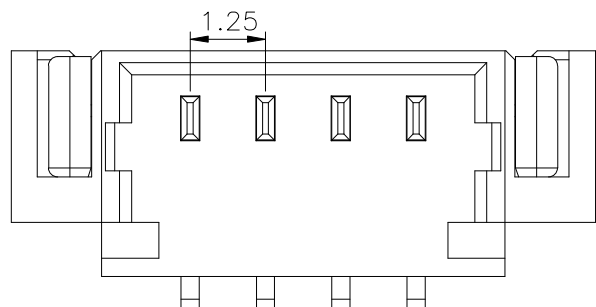


12	13	14	15
MAPX	MODIFICATION	DATE	DRAW



NOTES:

- 1.MATERIAL:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V_0
CONTACT: COPPER ALLOYS.
COVER: COPPER ALLOYS OR STEEL.
- 2.PLATING:
UNDERPLATE: NICKEL.

SPECIFICATIONS:

- Voltage Rating:125V AC DC
- Current Rating:1A AC,DC
- Withstanding voltage:500V AC 1/Minute
- Insulation Resistance:100MΩ Min
- Contact Resistance:20mΩ Max
- Temperatuer Range:-25℃ ~+ 85℃

MANUFACTURE DWG			 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: WAFER 1.25 立贴4P	
DECIMALS:	ANGLES:	PAR	WAFER-125L-4P	
X.X:±0.35	X.X':±3°	DWN		
X.XX:±0.25	X.XX:±2'	CHKD		
X.XXX:±0.15		APVD		
CUSTOMER COPY		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	REV:A